# Intel - 5SGSMD8N3F45I3N Datasheet

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## Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

## Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

| Details | |
|---|---|
| Product Status | Obsolete |
| Number of LABs/CLBs | 262400 |
| Number of Logic Elements/Cells | 695000 |
| Total RAM Bits | 51200000 |
| Number of I/O | 840 |
| Number of Gates | - |
| Voltage - Supply | 0.82V ~ 0.88V |
| Mounting Type | Surface Mount |
| Operating Temperature | -40°C ~ 100°C (TJ) |
| Package / Case | 1932-BBGA, FCBGA |
| Supplier Device Package | 1932-FBGA, FC (45x45) |
| Purchase URL | https://www.e-xfl.com/product-detail/intel/5sgsmd8n3f45i3n |

**Table 11. OCT Calibration Accuracy Specifications for Stratix V Devices (1) (Part 2 of 2)**

| Symbol | Description | Conditions | Calibration Accuracy | | | | Unit |
|---|---|---|---|---|---|---|---|
| | | | C1 | C2,I2 | C3,I3, I3YY | C4,I4 | |
| 50-Ω $R_S$ | Internal series termination with calibration (50-Ω setting) | $V_{CCIO}$ = 3.0, 2.5, 1.8, 1.5, 1.2 V | ±15 | ±15 | ±15 | ±15 | % |
| 34-Ω and 40-Ω $R_S$ | Internal series termination with calibration (34-Ω and 40-Ω setting) | $V_{CCIO}$ = 1.5, 1.35, 1.25, 1.2 V | ±15 | ±15 | ±15 | ±15 | % |
| 48-Ω, 60-Ω, 80-Ω, and 240-Ω $R_S$ | Internal series termination with calibration (48-Ω, 60-Ω, 80-Ω, and 240-Ω setting) | $V_{CCIO}$ = 1.2 V | ±15 | ±15 | ±15 | ±15 | % |
| 50-Ω $R_T$ | Internal parallel termination with calibration (50-Ω setting) | $V_{CCIO}$ = 2.5, 1.8, 1.5, 1.2 V | –10 to +40 | –10 to +40 | –10 to +40 | –10 to +40 | % |
| 20-Ω, 30-Ω, 40-Ω,60-Ω, and 120-Ω $R_T$ | Internal parallel termination with calibration (20-Ω, 30-Ω, 40-Ω, 60-Ω, and 120-Ω setting) | $V_{CCIO}$ = 1.5, 1.35, 1.25 V | –10 to +40 | –10 to +40 | –10 to +40 | –10 to +40 | % |
| 60-Ω and 120-Ω $R_T$ | Internal parallel termination with calibration (60-Ω and 120-Ω setting) | $V_{CCIO}$ = 1.2 | –10 to +40 | –10 to +40 | –10 to +40 | –10 to +40 | % |
| 25-Ω $R_{S\_left\_shift}$ | Internal left shift series termination with calibration (25-Ω $R_{S\_left\_shift}$ setting) | $V_{CCIO}$ = 3.0, 2.5, 1.8, 1.5, 1.2 V | ±15 | ±15 | ±15 | ±15 | % |

**Note to Table 11:**

(1) OCT calibration accuracy is valid at the time of calibration only.

Table 12 lists the Stratix V OCT without calibration resistance tolerance to PVT changes.

**Table 12. OCT Without Calibration Resistance Tolerance Specifications for Stratix V Devices (Part 1 of 2)**

| Symbol | Description | Conditions | Resistance Tolerance | | | | Unit |
|---|---|---|---|---|---|---|---|
| | | | C1 | C2,I2 | C3, I3, I3YY | C4, I4 | |
| 25-Ω R, 50-Ω $R_S$ | Internal series termination without calibration (25-Ω setting) | $V_{CCIO}$ = 3.0 and 2.5 V | ±30 | ±30 | ±40 | ±40 | % |
| 25-Ω $R_S$ | Internal series termination without calibration (25-Ω setting) | $V_{CCIO}$ = 1.8 and 1.5 V | ±30 | ±30 | ±40 | ±40 | % |
| 25-Ω $R_S$ | Internal series termination without calibration (25-Ω setting) | $V_{CCIO}$ = 1.2 V | ±35 | ±35 | ±50 | ±50 | % |

## Internal Weak Pull-Up Resistor

Table 16 lists the weak pull-up resistor values for Stratix V devices.

**Table 16. Internal Weak Pull-Up Resistor for Stratix V Devices (1), (2)**

| Symbol | Description | $V_{CCIO}$ Conditions (V) (3) | Value (4) | Unit |
|---|---|---|---|---|
| $R_{PU}$ | Value of the I/O pin pull-up resistor before and during configuration, as well as user mode if you enable the programmable pull-up resistor option. | 3.0 ±5% | 25 | kΩ |
| | | 2.5 ±5% | 25 | kΩ |
| | | 1.8 ±5% | 25 | kΩ |
| | | 1.5 ±5% | 25 | kΩ |
| | | 1.35 ±5% | 25 | kΩ |
| | | 1.25 ±5% | 25 | kΩ |
| | | 1.2 ±5% | 25 | kΩ |

**Notes to Table 16:**

(1) All I/O pins have an option to enable the weak pull-up resistor except the configuration, test, and JTAG pins.

(2) The internal weak pull-down feature is only available for the JTAG TCK pin. The typical value for this internal weak pull-down resistor is approximately 25 kΩ.

(3) The pin pull-up resistance values may be lower if an external source drives the pin higher than $V_{CCIO}$.

(4) These specifications are valid with a ±10% tolerance to cover changes over PVT.

## I/O Standard Specifications

Table 17 through Table 22 list the input voltage ($V_{IH}$ and $V_{IL}$), output voltage ($V_{OH}$ and $V_{OL}$), and current drive characteristics ($I_{OH}$ and $I_{OL}$) for various I/O standards supported by Stratix V devices. These tables also show the Stratix V device family I/O standard specifications. The $V_{OL}$ and $V_{OH}$ values are valid at the corresponding $I_{OH}$ and $I_{OL}$, respectively.

For an explanation of the terms used in Table 17 through Table 22, refer to "Glossary" on page 65. For tolerance calculations across all SSTL and HSTL I/O standards, refer to Altera knowledge base solution rd07262012_486.

**Table 17. Single-Ended I/O Standards for Stratix V Devices**

| I/O Standard | $V_{CCIO}$ (V) | | | $V_{IL}$ (V) | | $V_{IH}$ (V) | | $V_{OL}$ (V) | $V_{OH}$ (V) | $I_{OL}$ (mA) | $I_{OH}$ (mA) |
|---|---|---|---|---|---|---|---|---|---|---|---|
| | Min | Typ | Max | Min | Max | Min | Max | Max | Min | | |
| LVTTL | 2.85 | 3 | 3.15 | –0.3 | 0.8 | 1.7 | 3.6 | 0.4 | 2.4 | 2 | –2 |
| LVCMOS | 2.85 | 3 | 3.15 | –0.3 | 0.8 | 1.7 | 3.6 | 0.2 | $V_{CCIO}$ – 0.2 | 0.1 | –0.1 |
| 2.5 V | 2.375 | 2.5 | 2.625 | –0.3 | 0.7 | 1.7 | 3.6 | 0.4 | 2 | 1 | –1 |
| 1.8 V | 1.71 | 1.8 | 1.89 | –0.3 | 0.35 * $V_{CCIO}$ | 0.65 * $V_{CCIO}$ | $V_{CCIO}$ + 0.3 | 0.45 | $V_{CCIO}$ – 0.45 | 2 | –2 |
| 1.5 V | 1.425 | 1.5 | 1.575 | –0.3 | 0.35 * $V_{CCIO}$ | 0.65 * $V_{CCIO}$ | $V_{CCIO}$ + 0.3 | 0.25 * $V_{CCIO}$ | 0.75 * $V_{CCIO}$ | 2 | –2 |
| 1.2 V | 1.14 | 1.2 | 1.26 | –0.3 | 0.35 * $V_{CCIO}$ | 0.65 * $V_{CCIO}$ | $V_{CCIO}$ + 0.3 | 0.25 * $V_{CCIO}$ | 0.75 * $V_{CCIO}$ | 2 | –2 |

**Table 19. Single-Ended SSTL, HSTL, and HSUL I/O Standards Signal Specifications for Stratix V Devices (Part 2 of 2)**

| I/O Standard | $V_{IL(DC)}$ (V) | | $V_{IH(DC)}$ (V) | | $V_{IL(AC)}$ (V) | $V_{IH(AC)}$ (V) | $V_{OL}$ (V) | $V_{OH}$ (V) | $I_{ol}$ (mA) | $I_{oh}$ (mA) |
|---|---|---|---|---|---|---|---|---|---|---|
| | Min | Max | Min | Max | Max | Min | Max | Min | | |
| HSTL-18 Class I | — | $V_{REF}$ – 0.1 | $V_{REF}$ + 0.1 | — | $V_{REF}$ – 0.2 | $V_{REF}$ + 0.2 | 0.4 | $V_{CCIO}$ – 0.4 | 8 | –8 |
| HSTL-18 Class II | — | $V_{REF}$ – 0.1 | $V_{REF}$ + 0.1 | — | $V_{REF}$ – 0.2 | $V_{REF}$ + 0.2 | 0.4 | $V_{CCIO}$ – 0.4 | 16 | –16 |
| HSTL-15 Class I | — | $V_{REF}$ – 0.1 | $V_{REF}$ + 0.1 | — | $V_{REF}$ – 0.2 | $V_{REF}$ + 0.2 | 0.4 | $V_{CCIO}$ – 0.4 | 8 | –8 |
| HSTL-15 Class II | — | $V_{REF}$ – 0.1 | $V_{REF}$ + 0.1 | — | $V_{REF}$ – 0.2 | $V_{REF}$ + 0.2 | 0.4 | $V_{CCIO}$ – 0.4 | 16 | –16 |
| HSTL-12 Class I | –0.15 | $V_{REF}$ – 0.08 | $V_{REF}$ + 0.08 | $V_{CCIO}$ + 0.15 | $V_{REF}$ – 0.15 | $V_{REF}$ + 0.15 | 0.25* $V_{CCIO}$ | 0.75* $V_{CCIO}$ | 8 | –8 |
| HSTL-12 Class II | –0.15 | $V_{REF}$ – 0.08 | $V_{REF}$ + 0.08 | $V_{CCIO}$ + 0.15 | $V_{REF}$ – 0.15 | $V_{REF}$ + 0.15 | 0.25* $V_{CCIO}$ | 0.75* $V_{CCIO}$ | 16 | –16 |
| HSUL-12 | — | $V_{REF}$ – 0.13 | $V_{REF}$ + 0.13 | — | $V_{REF}$ – 0.22 | $V_{REF}$ + 0.22 | 0.1* $V_{CCIO}$ | 0.9* $V_{CCIO}$ | — | — |

**Table 20. Differential SSTL I/O Standards for Stratix V Devices**

| I/O Standard | $V_{CCIO}$ (V) | | | $V_{SWING(DC)}$ (V) | | $V_{X(AC)}$ (V) | | | $V_{SWING(AC)}$ (V) | |
|---|---|---|---|---|---|---|---|---|---|---|
| | Min | Typ | Max | Min | Max | Min | Typ | Max | Min | Max |
| SSTL-2 Class I, II | 2.375 | 2.5 | 2.625 | 0.3 | $V_{CCIO}$ + 0.6 | $V_{CCIO}/2$ – 0.2 | — | $V_{CCIO}/2$ + 0.2 | 0.62 | $V_{CCIO}$ + 0.6 |
| SSTL-18 Class I, II | 1.71 | 1.8 | 1.89 | 0.25 | $V_{CCIO}$ + 0.6 | $V_{CCIO}/2$ – 0.175 | — | $V_{CCIO}/2$ + 0.175 | 0.5 | $V_{CCIO}$ + 0.6 |
| SSTL-15 Class I, II | 1.425 | 1.5 | 1.575 | 0.2 | *(1)* | $V_{CCIO}/2$ – 0.15 | — | $V_{CCIO}/2$ + 0.15 | 0.35 | — |
| SSTL-135 Class I, II | 1.283 | 1.35 | 1.45 | 0.2 | *(1)* | $V_{CCIO}/2$ – 0.15 | $V_{CCIO}/2$ | $V_{CCIO}/2$ + 0.15 | $2(V_{IH(AC)} - V_{REF})$ | $2(V_{IL(AC)} - V_{REF})$ |
| SSTL-125 Class I, II | 1.19 | 1.25 | 1.31 | 0.18 | *(1)* | $V_{CCIO}/2$ – 0.15 | $V_{CCIO}/2$ | $V_{CCIO}/2$ + 0.15 | $2(V_{IH(AC)} - V_{REF})$ | — |
| SSTL-12 Class I, II | 1.14 | 1.2 | 1.26 | 0.18 | — | $V_{REF}$ –0.15 | $V_{CCIO}/2$ | $V_{REF}$ + 0.15 | –0.30 | 0.30 |

**Note to Table 20:**

(1) The maximum value for $V_{SWING(DC)}$ is not defined. However, each single-ended signal needs to be within the respective single-ended limits ($V_{IH(DC)}$ and $V_{IL(DC)}$).

**Table 21. Differential HSTL and HSUL I/O Standards for Stratix V Devices (Part 1 of 2)**

| I/O Standard | $V_{CCIO}$ (V) | | | $V_{DIF(DC)}$ (V) | | $V_{X(AC)}$ (V) | | | $V_{CM(DC)}$ (V) | | | $V_{DIF(AC)}$ (V) | |
|---|---|---|---|---|---|---|---|---|---|---|---|---|---|
| | Min | Typ | Max | Min | Max | Min | Typ | Max | Min | Typ | Max | Min | Max |
| HSTL-18 Class I, II | 1.71 | 1.8 | 1.89 | 0.2 | — | 0.78 | — | 1.12 | 0.78 | — | 1.12 | 0.4 | — |
| HSTL-15 Class I, II | 1.425 | 1.5 | 1.575 | 0.2 | — | 0.68 | — | 0.9 | 0.68 | — | 0.9 | 0.4 | — |

**Table 23. Transceiver Specifications for Stratix V GX and GS Devices (1) (Part 6 of 7)**

| Symbol/ Description | Conditions | Transceiver Speed Grade 1 | | | Transceiver Speed Grade 2 | | | Transceiver Speed Grade 3 | | | Unit |
|---|---|---|---|---|---|---|---|---|---|---|---|
| | | Min | Typ | Max | Min | Typ | Max | Min | Typ | Max | |
| Inter-transceiver block transmitter channel-to-channel skew | xN PMA bonded mode | — | — | 500 | — | — | 500 | — | — | 500 | ps |
| **CMU PLL** | | | | | | | | | | | |
| Supported Data Range | — | 600 | — | 12500 | 600 | — | 12500 | 600 | — | 8500/ 10312.5 (24) | Mbps |
| $t_{pll\_powerdown}$ (15) | — | 1 | — | — | 1 | — | — | 1 | — | — | µs |
| $t_{pll\_lock}$ (16) | — | — | — | 10 | — | — | 10 | — | — | 10 | µs |
| **ATX PLL** | | | | | | | | | | | |
| Supported Data Rate Range | VCO post-divider L=2 | 8000 | — | 14100 | 8000 | — | 12500 | 8000 | — | 8500/ 10312.5 (24) | Mbps |
| | L=4 | 4000 | — | 7050 | 4000 | — | 6600 | 4000 | — | 6600 | Mbps |
| | L=8 | 2000 | — | 3525 | 2000 | — | 3300 | 2000 | — | 3300 | Mbps |
| | L=8, Local/Central Clock Divider =2 | 1000 | — | 1762.5 | 1000 | — | 1762.5 | 1000 | — | 1762.5 | Mbps |
| $t_{pll\_powerdown}$ (15) | — | 1 | — | — | 1 | — | — | 1 | — | — | µs |
| $t_{pll\_lock}$ (16) | — | — | — | 10 | — | — | 10 | — | — | 10 | µs |
| **fPLL** | | | | | | | | | | | |
| Supported Data Range | — | 600 | — | 3250/ 3125 (25) | 600 | — | 3250/ 3125 (25) | 600 | — | 3250/ 3125 (25) | Mbps |
| $t_{pll\_powerdown}$ (15) | — | 1 | — | — | 1 | — | — | 1 | — | — | µs |

Table 24 shows the maximum transmitter data rate for the clock network.

**Table 24. Clock Network Maximum Data Rate Transmitter Specifications** *(1)*

| Clock Network | ATX PLL | | | CMU PLL *(2)* | | | fPLL | | |
|---|---|---|---|---|---|---|---|---|---|
| | Non-bonded Mode (Gbps) | Bonded Mode (Gbps) | Channel Span | Non-bonded Mode (Gbps) | Bonded Mode (Gbps) | Channel Span | Non-bonded Mode (Gbps) | Bonded Mode (Gbps) | Channel Span |
| x1 *(3)* | 14.1 | — | 6 | 12.5 | — | 6 | 3.125 | — | 3 |
| x6 *(3)* | — | 14.1 | 6 | — | 12.5 | 6 | — | 3.125 | 6 |
| x6 PLL Feedback *(4)* | — | 14.1 | Side-wide | — | 12.5 | Side-wide | — | — | — |
| xN (PCIe) | — | 8.0 | 8 | — | 5.0 | 8 | — | — | — |
| xN (Native PHY IP) | 8.0 | 8.0 | Up to 13 channels above and below PLL | 7.99 | 7.99 | Up to 13 channels above and below PLL | 3.125 | 3.125 | Up to 13 channels above and below PLL |
| | — | 8.01 to 9.8304 | Up to 7 channels above and below PLL | | | | | | |

**Notes to Table 24:**

(1) Valid data rates below the maximum specified in this table depend on the reference clock frequency and the PLL counter settings. Check the MegaWizard message during the PHY IP instantiation.

(2) ATX PLL is recommended at 8 Gbps and above data rates for improved jitter performance.

(3) Channel span is within a transceiver bank.

(4) Side-wide channel bonding is allowed up to the maximum supported by the PHY IP.

**Table 28. Transceiver Specifications for Stratix V GT Devices (Part 5 of 5) (1)**

| Symbol/ Description | Conditions | Transceiver Speed Grade 2 | | | Transceiver Speed Grade 3 | | | Unit |
|---|---|---|---|---|---|---|---|---|
| | | Min | Typ | Max | Min | Typ | Max | |
| $t_{pll\_lock}$ (14) | — | — | — | 10 | — | — | 10 | µs |

**Notes to Table 28:**

(1) Speed grades shown refer to the PMA Speed Grade in the device ordering code. The maximum data rate could be restricted by the Core/PCS speed grade. Contact your Altera Sales Representative for the maximum data rate specifications in each speed grade combination offered. For more information about device ordering codes, refer to the *Stratix V Device Overview*.

(2) The reference clock common mode voltage is equal to the VCCR_GXB power supply level.

(3) The device cannot tolerate prolonged operation at this absolute maximum.

(4) The differential eye opening specification at the receiver input pins assumes that receiver equalization is disabled. If you enable receiver equalization, the receiver circuitry can tolerate a lower minimum eye opening, depending on the equalization level.

(5) Refer to Figure 5 for the GT channel AC gain curves. The total effective AC gain is the AC gain minus the DC gain.

(6) Refer to Figure 6 for the GT channel DC gain curves.

(7) CFP2 optical modules require the host interface to have the receiver data pins differentially terminated with 100 Ω. The internal OCT feature is available after the Stratix V FPGA configuration is completed. Altera recommends that FPGA configuration is completed before inserting the optical module. Otherwise, minimize unnecessary removal and insertion with unconfigured devices.

(8) Specifications for this parameter are the same as for Stratix V GX and GS devices. See Table 23 for specifications.

(9) $t_{LTR}$ is the time required for the receive CDR to lock to the input reference clock frequency after coming out of reset.

(10) $t_{LTD}$ is time required for the receiver CDR to start recovering valid data after the `rx_is_lockedtodata` signal goes high.

(11) $t_{LTD\_manual}$ is the time required for the receiver CDR to start recovering valid data after the `rx_is_lockedtodata` signal goes high when the CDR is functioning in the manual mode.

(12) $t_{LTR\_LTD\_manual}$ is the time the receiver CDR must be kept in lock to reference (LTR) mode after the `rx_is_lockedtoref` signal goes high when the CDR is functioning in the manual mode.

(13) `tpll_powerdown` is the PLL powerdown minimum pulse width.

(14) `tpll_lock` is the time required for the transmitter CMU/ATX PLL to lock to the input reference clock frequency after coming out of reset.

(15) To calculate the REFCLK rms phase jitter requirement for PCIe at reference clock frequencies other than 100 MHz, use the following formula: REFCLK rms phase jitter at f(MHz) = REFCLK rms phase jitter at 100 MHz × 100/f.

(16) The maximum peak to peak differential input voltage $V_{ID}$ after device configuration is equal to 4 × (absolute $V_{MAX}$ for receiver pin - $V_{ICM}$).

(17) For ES devices, RREF is 2000 Ω ±1%.

(18) To calculate the REFCLK phase noise requirement at frequencies other than 622 MHz, use the following formula: REFCLK phase noise at f(MHz) = REFCLK phase noise at 622 MHz + 20*log(f/622).

(19) SFP/+ optical modules require the host interface to have RD+/- differentially terminated with 100 Ω. The internal OCT feature is available after the Stratix V FPGA configuration is completed. Altera recommends that FPGA configuration is completed before inserting the optical module. Otherwise, minimize unnecessary removal and insertion with unconfigured devices.

(20) Refer to Figure 4.

(21) For oversampling design to support data rates less than the minimum specification, the CDR needs to be in LTR mode only.

(22) This supply follows VCCR_GXB for both GX and GT channels.

(23) When you use fPLL as a TXPLL of the transceiver.

Table 29 shows the $V_{OD}$ settings for the GT channel.

**Table 29. Typical $V_{OD}$ Setting for GT Channel, TX Termination = 100 Ω**

| Symbol | $V_{OD}$ Setting | $V_{OD}$ Value (mV) |
|---|---|---|
| $V_{OD}$ differential peak to peak typical (1) | 0 | 0 |
| | 1 | 200 |
| | 2 | 400 |
| | 3 | 600 |
| | 4 | 800 |
| | 5 | 1000 |

**Note:**

(1) Refer to Figure 4.

Figure 6 shows the Stratix V DC gain curves for GT channels.

**Figure 6. DC Gain Curves for GT Channels**

## Transceiver Characterization

This section summarizes the Stratix V transceiver characterization results for compliance with the following protocols:

- Interlaken
- 40G (XLAUI)/100G (CAUI)
- 10GBase-KR
- QSGMII
- XAUI
- SFI
- Gigabit Ethernet (Gbe / GIGE)
- SPAUI
- Serial Rapid IO (SRIO)
- CPRI
- OBSAI
- Hyper Transport (HT)
- SATA
- SAS
- CEI

- XFI
- ASI
- HiGig/HiGig+
- HiGig2/HiGig2+
- Serial Data Converter (SDC)
- GPON
- SDI
- SONET
- Fibre Channel (FC)
- PCIe
- QPI
- SFF-8431

Download the Stratix V Characterization Report Tool to view the characterization report summary for these protocols.

# Core Performance Specifications

This section describes the clock tree, phase-locked loop (PLL), digital signal processing (DSP), memory blocks, configuration, and JTAG specifications.

## Clock Tree Specifications

Table 30 lists the clock tree specifications for Stratix V devices.

**Table 30. Clock Tree Performance for Stratix V Devices** *(1)*

| Symbol | Performance | | | Unit |
|---|---|---|---|---|
| | C1, C2, C2L, I2, and I2L | C3, I3, I3L, and I3YY | C4, I4 | |
| Global and Regional Clock | 717 | 650 | 580 | MHz |
| Periphery Clock | 550 | 500 | 500 | MHz |

**Note to Table 30:**

(1) The Stratix V ES devices are limited to 600 MHz core clock tree performance.

**Table 33. Memory Block Performance Specifications for Stratix V Devices (1), (2) (Part 2 of 2)**

| Memory | Mode | Resources Used | | Performance | | | | | | | Unit |
|---|---|---|---|---|---|---|---|---|---|---|---|
| | | ALUTs | Memory | C1 | C2, C2L | C3 | C4 | I2, I2L | I3, I3L, I3YY | I4 | |
| M20K Block | Single-port, all supported widths | 0 | 1 | 700 | 700 | 650 | 550 | 700 | 500 | 450 | MHz |
| | Simple dual-port, all supported widths | 0 | 1 | 700 | 700 | 650 | 550 | 700 | 500 | 450 | MHz |
| | Simple dual-port with the read-during-write option set to **Old Data**, all supported widths | 0 | 1 | 525 | 525 | 455 | 400 | 525 | 455 | 400 | MHz |
| | Simple dual-port with ECC enabled, 512 × 32 | 0 | 1 | 450 | 450 | 400 | 350 | 450 | 400 | 350 | MHz |
| | Simple dual-port with ECC and optional pipeline registers enabled, 512 × 32 | 0 | 1 | 600 | 600 | 500 | 450 | 600 | 500 | 450 | MHz |
| | True dual port, all supported widths | 0 | 1 | 700 | 700 | 650 | 550 | 700 | 500 | 450 | MHz |
| | ROM, all supported widths | 0 | 1 | 700 | 700 | 650 | 550 | 700 | 500 | 450 | MHz |

**Notes to Table 33:**

(1) To achieve the maximum memory block performance, use a memory block clock that comes through global clock routing from an on-chip PLL set to **50%** output duty cycle. Use the Quartus II software to report timing for this and other memory block clocking schemes.

(2) When you use the error detection cyclical redundancy check (CRC) feature, there is no degradation in $F_{MAX}$.

(3) The $F_{MAX}$ specification is only achievable with Fitter options, **MLAB Implementation In 16-Bit Deep Mode** enabled.

## Temperature Sensing Diode Specifications

Table 34 lists the internal TSD specification.

**Table 34. Internal Temperature Sensing Diode Specification**

| Temperature Range | Accuracy | Offset Calibrated Option | Sampling Rate | Conversion Time | Resolution | Minimum Resolution with no Missing Codes |
|---|---|---|---|---|---|---|
| –40°C to 100°C | ±8°C | No | 1 MHz, 500 KHz | < 100 ms | 8 bits | 8 bits |

Table 35 lists the specifications for the Stratix V external temperature sensing diode.

**Table 35. External Temperature Sensing Diode Specifications for Stratix V Devices**

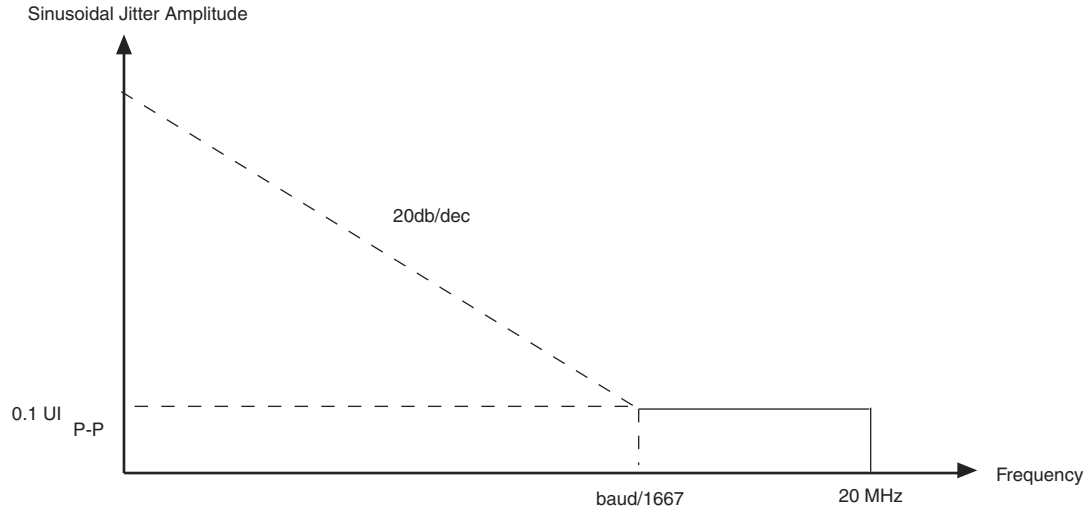
| Description | Min | Typ | Max | Unit |
|---|---|---|---|---|
| $I_{bias}$, diode source current | 8 | — | 200 | μA |
| $V_{bias,}$ voltage across diode | 0.3 | — | 0.9 | V |
| Series resistance | — | — | < 1 | Ω |
| Diode ideality factor | 1.006 | 1.008 | 1.010 | — |

**Table 38. LVDS Soft-CDR/DPA Sinusoidal Jitter Mask Values for a Data Rate ≥ 1.25 Gbps**

| Jitter Frequency (Hz) | | Sinusoidal Jitter (UI) |
|---|---|---|
| F1 | 10,000 | 25.000 |
| F2 | 17,565 | 25.000 |
| F3 | 1,493,000 | 0.350 |
| F4 | 50,000,000 | 0.350 |

Figure 9 shows the **LVDS** soft-CDR/DPA sinusoidal jitter tolerance specification for a data rate < 1.25 Gbps.

**Figure 9. LVDS Soft-CDR/DPA Sinusoidal Jitter Tolerance Specification for a Data Rate < 1.25 Gbps**




## DLL Range, DQS Logic Block, and Memory Output Clock Jitter Specifications

Table 39 lists the DLL range specification for Stratix V devices. The DLL is always in 8-tap mode in Stratix V devices.

**Table 39. DLL Range Specifications for Stratix V Devices (1)**

| C1 | C2, C2L, I2, I2L | C3, I3, I3L, I3YY | C4,I4 | Unit |
|---|---|---|---|---|
| 300-933 | 300-933 | 300-890 | 300-890 | MHz |

**Note to Table 39:**

(1) Stratix V devices support memory interface frequencies lower than 300 MHz, although the reference clock that feeds the DLL must be at least 300 MHz. To support interfaces below 300 MHz, multiply the reference clock feeding the DLL to ensure the frequency is within the supported range of the DLL.

Table 40 lists the DQS phase offset delay per stage for Stratix V devices.

**Table 40. DQS Phase Offset Delay Per Setting for Stratix V Devices (1), (2) (Part 1 of 2)**

| Speed Grade | Min | Max | Unit |
|---|---|---|---|
| C1 | 8 | 14 | ps |
| C2, C2L, I2, I2L | 8 | 14 | ps |
| C3,I3, I3L, I3YY | 8 | 15 | ps |

### Duty Cycle Distortion (DCD) Specifications

Table 44 lists the worst-case DCD for Stratix V devices.

**Table 44. Worst-Case DCD on Stratix V I/O Pins** *(1)*

| Symbol | C1 | | C2, C2L, I2, I2L | | C3, I3, I3L, I3YY | | C4,I4 | | Unit |
|---|---|---|---|---|---|---|---|---|---|
| | Min | Max | Min | Max | Min | Max | Min | Max | |
| Output Duty Cycle | 45 | 55 | 45 | 55 | 45 | 55 | 45 | 55 | % |

**Note to Table 44:**

(1) The DCD numbers do not cover the core clock network.

# Configuration Specification

## POR Delay Specification

Power-on reset (POR) delay is defined as the delay between the time when all the power supplies monitored by the POR circuitry reach the minimum recommended operating voltage to the time when the nSTATUS is released high and your device is ready to begin configuration.

For more information about the POR delay, refer to the *Hot Socketing and Power-On Reset in Stratix V Devices* chapter.

Table 45 lists the fast and standard POR delay specification.

**Table 45. Fast and Standard POR Delay Specification** *(1)*

| POR Delay | Minimum | Maximum |
|---|---|---|
| Fast | 4 ms | 12 ms |
| Standard | 100 ms | 300 ms |

**Note to Table 45:**

(1) You can select the POR delay based on the MSEL settings as described in the MSEL Pin Settings section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.

## JTAG Configuration Specifications

Table 46 lists the JTAG timing parameters and values for Stratix V devices.

**Table 46. JTAG Timing Parameters and Values for Stratix V Devices**

| Symbol | Description | Min | Max | Unit |
|---|---|---|---|---|
| $t_{JCP}$ | TCK clock period *(2)* | 30 | — | ns |
| $t_{JCP}$ | TCK clock period *(2)* | 167 | — | ns |
| $t_{JCH}$ | TCK clock high time *(2)* | 14 | — | ns |
| $t_{JCL}$ | TCK clock low time *(2)* | 14 | — | ns |
| $t_{JPSU\ (TDI)}$ | TDI JTAG port setup time | 2 | — | ns |
| $t_{JPSU\ (TMS)}$ | TMS JTAG port setup time | 3 | — | ns |

**Table 48. Minimum Configuration Time Estimation for Stratix V Devices**

| Variant | Member Code | Active Serial (1) | | | Fast Passive Parallel (2) | | |
|---|---|---|---|---|---|---|---|
| | | Width | DCLK (MHz) | Min Config Time (s) | Width | DCLK (MHz) | Min Config Time (s) |
| GS | D3 | 4 | 100 | 0.344 | 32 | 100 | 0.043 |
| | D4 | 4 | 100 | 0.534 | 32 | 100 | 0.067 |
| | | 4 | 100 | 0.344 | 32 | 100 | 0.043 |
| | D5 | 4 | 100 | 0.534 | 32 | 100 | 0.067 |
| | D6 | 4 | 100 | 0.741 | 32 | 100 | 0.093 |
| | D8 | 4 | 100 | 0.741 | 32 | 100 | 0.093 |
| E | E9 | 4 | 100 | 0.857 | 32 | 100 | 0.107 |
| | EB | 4 | 100 | 0.857 | 32 | 100 | 0.107 |

**Notes to Table 48:**

(1) DCLK frequency of 100 MHz using external CLKUSR.

(2) Max FPGA FPP bandwidth may exceed bandwidth available from some external storage or control logic.

# Fast Passive Parallel Configuration Timing

This section describes the fast passive parallel (FPP) configuration timing parameters for Stratix V devices.

## DCLK-to-DATA[] Ratio for FPP Configuration

FPP configuration requires a different DCLK-to-DATA[] ratio when you enable the design security, decompression, or both features. Table 49 lists the DCLK-to-DATA[] ratio for each combination.

**Table 49. DCLK-to-DATA[] Ratio (1) (Part 1 of 2)**

| Configuration Scheme | Decompression | Design Security | DCLK-to-DATA[] Ratio |
|---|---|---|---|
| FPP ×8 | Disabled | Disabled | 1 |
| | Disabled | Enabled | 1 |
| | Enabled | Disabled | 2 |
| | Enabled | Enabled | 2 |
| FPP ×16 | Disabled | Disabled | 1 |
| | Disabled | Enabled | 2 |
| | Enabled | Disabled | 4 |
| | Enabled | Enabled | 4 |

Table 50 lists the timing parameters for Stratix V devices for FPP configuration when the DCLK-to-DATA[] ratio is 1.

**Table 50. FPP Timing Parameters for Stratix V Devices (1)**

| Symbol | Parameter | Minimum | Maximum | Units |
|---|---|---|---|---|
| $t_{CF2CD}$ | nCONFIG low to CONF_DONE low | — | 600 | ns |
| $t_{CF2ST0}$ | nCONFIG low to nSTATUS low | — | 600 | ns |
| $t_{CFG}$ | nCONFIG low pulse width | 2 | — | µs |
| $t_{STATUS}$ | nSTATUS low pulse width | 268 | 1,506 (2) | µs |
| $t_{CF2ST1}$ | nCONFIG high to nSTATUS high | — | 1,506 (3) | µs |
| $t_{CF2CK}$ (6) | nCONFIG high to first rising edge on DCLK | 1,506 | — | µs |
| $t_{ST2CK}$ (6) | nSTATUS high to first rising edge of DCLK | 2 | — | µs |
| $t_{DSU}$ | DATA[] setup time before rising edge on DCLK | 5.5 | — | ns |
| $t_{DH}$ | DATA[] hold time after rising edge on DCLK | 0 | — | ns |
| $t_{CH}$ | DCLK high time | $0.45 \times 1/f_{MAX}$ | — | s |
| $t_{CL}$ | DCLK low time | $0.45 \times 1/f_{MAX}$ | — | s |
| $t_{CLK}$ | DCLK period | $1/f_{MAX}$ | — | s |
| $f_{MAX}$ | DCLK frequency (FPP ×8/×16) | — | 125 | MHz |
| | DCLK frequency (FPP ×32) | — | 100 | MHz |
| $t_{CD2UM}$ | CONF_DONE high to user mode (4) | 175 | 437 | µs |
| $t_{CD2CU}$ | CONF_DONE high to CLKUSR enabled | 4 × maximum DCLK period | — | — |
| $t_{CD2UMC}$ | CONF_DONE high to user mode with CLKUSR option on | $t_{CD2CU}$ + (8576 × CLKUSR period) (5) | — | — |

**Notes to Table 50:**

(1) Use these timing parameters when the decompression and design security features are disabled.

(2) This value is applicable if you do not delay configuration by extending the nCONFIG or nSTATUS low pulse width.

(3) This value is applicable if you do not delay configuration by externally holding the nSTATUS low.

(4) The minimum and maximum numbers apply only if you chose the internal oscillator as the clock source for initializing the device.

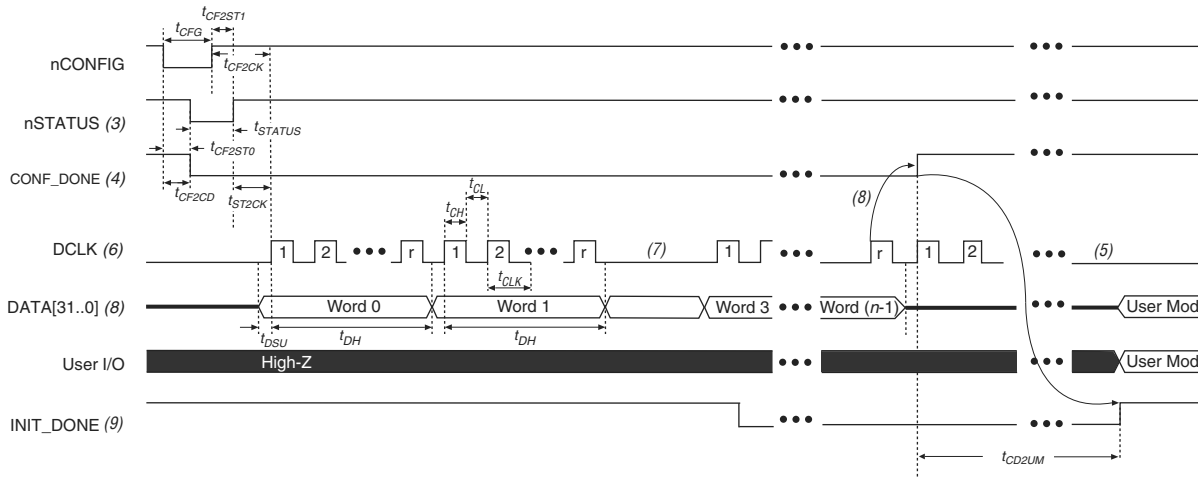
(5) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on these pins, refer to the Initialization section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.

(6) If nSTATUS is monitored, follow the $t_{ST2CK}$ specification. If nSTATUS is not monitored, follow the $t_{CF2CK}$ specification.

## FPP Configuration Timing when DCLK-to-DATA [] > 1

Figure 13 shows the timing waveform for FPP configuration when using a MAX II device, MAX V device, or microprocessor as an external host. This waveform shows timing when the DCLK-to-DATA[] ratio is more than 1.

**Figure 13. FPP Configuration Timing Waveform When the DCLK-to-DATA[] Ratio is >1** *(1), (2)*




**Notes to Figure 13:**

(1) Use this timing waveform and parameters when the DCLK-to-DATA[] ratio is >1. To find out the DCLK-to-DATA[] ratio for your system, refer to Table 49 on page 55.

(2) The beginning of this waveform shows the device in user mode. In user mode, nCONFIG, nSTATUS, and CONF_DONE are at logic high levels. When nCONFIG is pulled low, a reconfiguration cycle begins.

(3) After power-up, the Stratix V device holds nSTATUS low for the time as specified by the POR delay.

(4) After power-up, before and during configuration, CONF_DONE is low.

(5) Do not leave DCLK floating after configuration. You can drive it high or low, whichever is more convenient.

(6) "r" denotes the DCLK-to-DATA[] ratio. For the DCLK-to-DATA[] ratio based on the decompression and the design security feature enable settings, refer to Table 49 on page 55.

(7) If needed, pause DCLK by holding it low. When DCLK restarts, the external host must provide data on the DATA[31..0] pins prior to sending the first DCLK rising edge.

(8) To ensure a successful configuration, send the entire configuration data to the Stratix V device. CONF_DONE is released high after the Stratix V device receives all the configuration data successfully. After CONF_DONE goes high, send two additional falling edges on DCLK to begin initialization and enter user mode.

(9) After the option bit to enable the INIT_DONE pin is configured into the device, the INIT_DONE goes low.

Table 54 lists the PS configuration timing parameters for Stratix V devices.

**Table 54. PS Timing Parameters for Stratix V Devices**

| Symbol | Parameter | Minimum | Maximum | Units |
|---|---|---|---|---|
| $t_{CF2CD}$ | nCONFIG low to CONF_DONE low | — | 600 | ns |
| $t_{CF2ST0}$ | nCONFIG low to nSTATUS low | — | 600 | ns |
| $t_{CFG}$ | nCONFIG low pulse width | 2 | — | µs |
| $t_{STATUS}$ | nSTATUS low pulse width | 268 | 1,506 (1) | µs |
| $t_{CF2ST1}$ | nCONFIG high to nSTATUS high | — | 1,506 (2) | µs |
| $t_{CF2CK}$ (5) | nCONFIG high to first rising edge on DCLK | 1,506 | — | µs |
| $t_{ST2CK}$ (5) | nSTATUS high to first rising edge of DCLK | 2 | — | µs |
| $t_{DSU}$ | DATA[] setup time before rising edge on DCLK | 5.5 | — | ns |
| $t_{DH}$ | DATA[] hold time after rising edge on DCLK | 0 | — | ns |
| $t_{CH}$ | DCLK high time | $0.45 \times 1/f_{MAX}$ | — | s |
| $t_{CL}$ | DCLK low time | $0.45 \times 1/f_{MAX}$ | — | s |
| $t_{CLK}$ | DCLK period | $1/f_{MAX}$ | — | s |
| $f_{MAX}$ | DCLK frequency | — | 125 | MHz |
| $t_{CD2UM}$ | CONF_DONE high to user mode (3) | 175 | 437 | µs |
| $t_{CD2CU}$ | CONF_DONE high to CLKUSR enabled | 4 × maximum DCLK period | — | — |
| $t_{CD2UMC}$ | CONF_DONE high to user mode with CLKUSR option on | $t_{CD2CU}$ + (8576 × CLKUSR period) (4) | — | — |

**Notes to Table 54:**

(1) This value is applicable if you do not delay configuration by extending the nCONFIG or nSTATUS low pulse width.

(2) This value is applicable if you do not delay configuration by externally holding the nSTATUS low.

(3) The minimum and maximum numbers apply only if you choose the internal oscillator as the clock source for initializing the device.

(4) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on these pins, refer to the "Initialization" section.

(5) If nSTATUS is monitored, follow the $t_{ST2CK}$ specification. If nSTATUS is not monitored, follow the $t_{CF2CK}$ specification.

## Initialization

Table 55 lists the initialization clock source option, the applicable configuration schemes, and the maximum frequency.

**Table 55. Initialization Clock Source Option and the Maximum Frequency**

| Initialization Clock Source | Configuration Schemes | Maximum Frequency | Minimum Number of Clock Cycles (1) |
|---|---|---|---|
| Internal Oscillator | AS, PS, FPP | 12.5 MHz | 8576 |
| CLKUSR | AS, PS, FPP (2) | 125 MHz | |
| DCLK | PS, FPP | 125 MHz | |

**Notes to Table 55:**

(1) The minimum number of clock cycles required for device initialization.

(2) To enable CLKUSR as the initialization clock source, turn on the **Enable user-supplied start-up clock (CLKUSR)** option in the Quartus II software from the **General** panel of the **Device and Pin Options** dialog box.

## Remote System Upgrades

Table 56 lists the timing parameter specifications for the remote system upgrade circuitry.

**Table 56. Remote System Upgrade Circuitry Timing Specifications**

| Parameter | Minimum | Maximum | Unit |
|---|---|---|---|
| $t_{RU\_nCONFIG}$ (1) | 250 | — | ns |
| $t_{RU\_nRSTIMER}$ (2) | 250 | — | ns |

**Notes to Table 56:**

(1) This is equivalent to strobing the reconfiguration input of the ALTREMOTE_UPDATE megafunction high for the minimum timing specification. For more information, refer to the Remote System Upgrade State Machine section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.

(2) This is equivalent to strobing the reset_timer input of the ALTREMOTE_UPDATE megafunction high for the minimum timing specification. For more information, refer to the User Watchdog Timer section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.

## User Watchdog Internal Circuitry Timing Specification

Table 57 lists the operating range of the 12.5-MHz internal oscillator.

**Table 57. 12.5-MHz Internal Oscillator Specifications**

| Minimum | Typical | Maximum | Units |
|---|---|---|---|
| 5.3 | 7.9 | 12.5 | MHz |

# I/O Timing

Altera offers two ways to determine I/O timing—the Excel-based I/O Timing and the Quartus II Timing Analyzer.

Excel-based I/O timing provides pin timing performance for each device density and speed grade. The data is typically used prior to designing the FPGA to get an estimate of the timing budget as part of the link timing analysis. The Quartus II Timing Analyzer provides a more accurate and precise I/O timing data based on the specifics of the design after you complete place-and-route.

You can download the Excel-based I/O Timing spreadsheet from the Stratix V Devices Documentation web page.

## Programmable IOE Delay

Table 58 lists the Stratix V IOE programmable delay settings.

**Table 58. IOE Programmable Delay for Stratix V Devices (Part 1 of 2)**

| Parameter (1) | Available Settings | Min Offset (2) | Fast Model | | Slow Model | | | | | | | |
|---|---|---|---|---|---|---|---|---|---|---|---|---|
| | | | Industrial | Commercial | C1 | C2 | C3 | C4 | I2 | I3, I3YY | I4 | Unit |
| D1 | 64 | 0 | 0.464 | 0.493 | 0.838 | 0.838 | 0.924 | 1.011 | 0.844 | 0.921 | 1.006 | ns |
| D2 | 32 | 0 | 0.230 | 0.244 | 0.415 | 0.415 | 0.459 | 0.503 | 0.417 | 0.456 | 0.500 | ns |

**Table 60. Glossary (Part 2 of 4)**

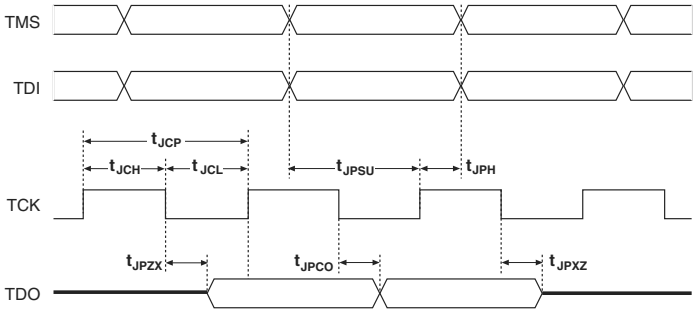
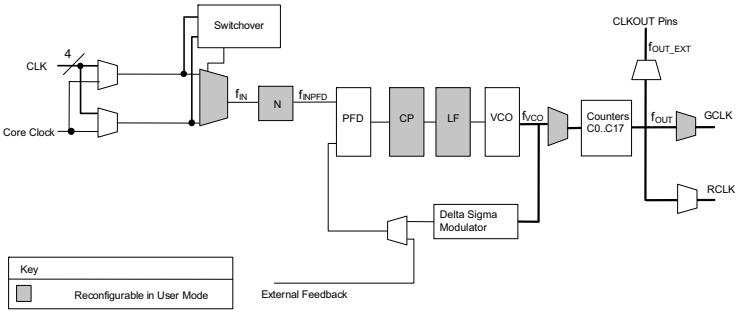
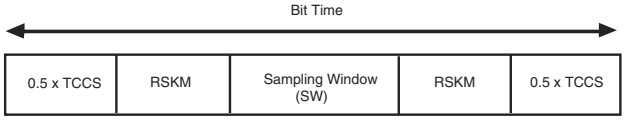
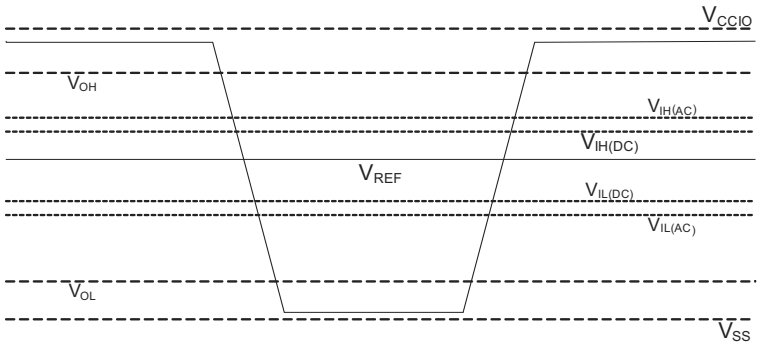
| Letter | Subject | Definitions |
|---|---|---|
| G<br>H<br>I | — | — |
| J | J | High-speed I/O block—Deserialization factor (width of parallel data bus). |
| J | JTAG Timing Specifications | JTAG Timing Specifications:<br>  <br> |
| K<br>L<br>M<br>N<br>O | — | — |
| P | **PLL Specifications** | **Diagram of PLL Specifications** *(1)*<br>  <br><br>**Note:**<br>(1) `Core Clock` can only be fed by dedicated clock input pins or PLL outputs. |
| Q | — | — |
| R | $R_L$ | Receiver differential input discrete resistor (external to the Stratix V device). |

**Table 60. Glossary (Part 3 of 4)**

| Letter | Subject | Definitions |
|---|---|---|
| S | **SW (sampling window)** | Timing Diagram—the period of time during which the data must be valid in order to capture it correctly. The setup and hold times determine the ideal strobe position within the sampling window, as shown:<br>  |
| | Single-ended voltage referenced I/O standard | The JEDEC standard for **SSTL** and **HSTL** I/O defines both the AC and DC input signal values. The AC values indicate the voltage levels at which the receiver must meet its timing specifications. The DC values indicate the voltage levels at which the final logic state of the receiver is unambiguously defined. After the receiver input has crossed the AC value, the receiver changes to the new logic state.<br>The new logic state is then maintained as long as the input stays beyond the DC threshold. This approach is intended to provide predictable receiver timing in the presence of input waveform ringing:<br>*Single-Ended Voltage Referenced I/O Standard*<br>  |
| T | $t_C$ | High-speed receiver and transmitter input and output clock period. |
| | **TCCS (channel-to-channel-skew)** | The timing difference between the fastest and slowest output edges, including $t_{CO}$ variation and clock skew, across channels driven by the same PLL. The clock is included in the TCCS measurement (refer to the *Timing Diagram* figure under **SW** in this table). |
| | $t_{DUTY}$ | High-speed I/O block—Duty cycle on the high-speed transmitter output clock. |
| | | **Timing Unit Interval (TUI)**<br>The timing budget allowed for skew, propagation delays, and the data sampling window. (TUI = 1/(receiver input clock frequency multiplication factor) = $t_C/w$) |
| | $t_{FALL}$ | Signal high-to-low transition time (80-20%) |
| | $t_{INCCJ}$ | Cycle-to-cycle jitter tolerance on the PLL clock input. |
| | $t_{OUTPJ\_IO}$ | Period jitter on the general purpose I/O driven by a PLL. |
| | $t_{OUTPJ\_DC}$ | Period jitter on the dedicated clock output driven by a PLL. |
| | $t_{RISE}$ | Signal low-to-high transition time (20-80%) |
| U | — | — |

# Document Revision History

Table 61 lists the revision history for this chapter.

**Table 61. Document Revision History (Part 1 of 3)**

| Date | Version | Changes |
|---|---|---|
| June 2018 | 3.9 | ■ Added the “Stratix V Device Overshoot Duration” figure. |
| April 2017 | 3.8 | ■ Added a footnote to the “High-Speed I/O Specifications for Stratix V Devices” table.<br>■ Changed the minimum value for $t_{CD2UMC}$ in the “PS Timing Parameters for Stratix V Devices” table.<br>■ Changed the condition for 100-Ω $R_D$ in the “OCT Without Calibration Resistance Tolerance Specifications for Stratix V Devices” table.<br>■ Changed the minimum value for $t_{CD2UMC}$ in the “AS Timing Parameters for AS ´1 and AS ´4 Configurations in Stratix V Devices” table<br>■ Changed the minimum value for $t_{CD2UMC}$ in the “FPP Timing Parameters for Stratix V Devices When the DCLK-to-DATA[] Ratio is >1” table.<br>■ Changed the minimum value for $t_{CD2UMC}$ in the “FPP Timing Parameters for Stratix V Devices When the DCLK-to-DATA[] Ratio is >1” table.<br>■ Changed the minimum number of clock cycles value in the “Initialization Clock Source Option and the Maximum Frequency” table. |
| June 2016 | 3.7 | ■ Added the $V_{ID}$ minimum specification for LVPECL in the “Differential I/O Standard Specifications for Stratix V Devices” table<br>■ Added the $I_{OUT}$ specification to the “Absolute Maximum Ratings for Stratix V Devices” table. |
| December 2015 | 3.6 | ■ Added a footnote to the “High-Speed I/O Specifications for Stratix V Devices” table. |
| December 2015 | 3.5 | ■ Changed the transmitter, receiver, and ATX PLL data rate specifications in the “Transceiver Specifications for Stratix V GX and GS Devices” table.<br>■ Changed the configuration .rbf sizes in the “Uncompressed .rbf Sizes for Stratix V Devices” table. |
| July 2015 | 3.4 | ■ Changed the data rate specification for transceiver speed grade 3 in the following tables:<br>  ■ “Transceiver Specifications for Stratix V GX and GS Devices”<br>  ■ “Stratix V Standard PCS Approximate Maximum Date Rate”<br>  ■ “Stratix V 10G PCS Approximate Maximum Data Rate”<br>■ Changed the conditions for reference clock rise and fall time, and added a note to the “Transceiver Specifications for Stratix V GX and GS Devices” table.<br>■ Added a note to the “Minimum differential eye opening at receiver serial input pins” specification in the “Transceiver Specifications for Stratix V GX and GS Devices” table.<br>■ Changed the $t_{CO}$ maximum value in the “AS Timing Parameters for AS ´1 and AS ´4 Configurations in Stratix V Devices” table.<br>■ Removed the CDR ppm tolerance specification from the “Transceiver Specifications for Stratix V GX and GS Devices” table. |